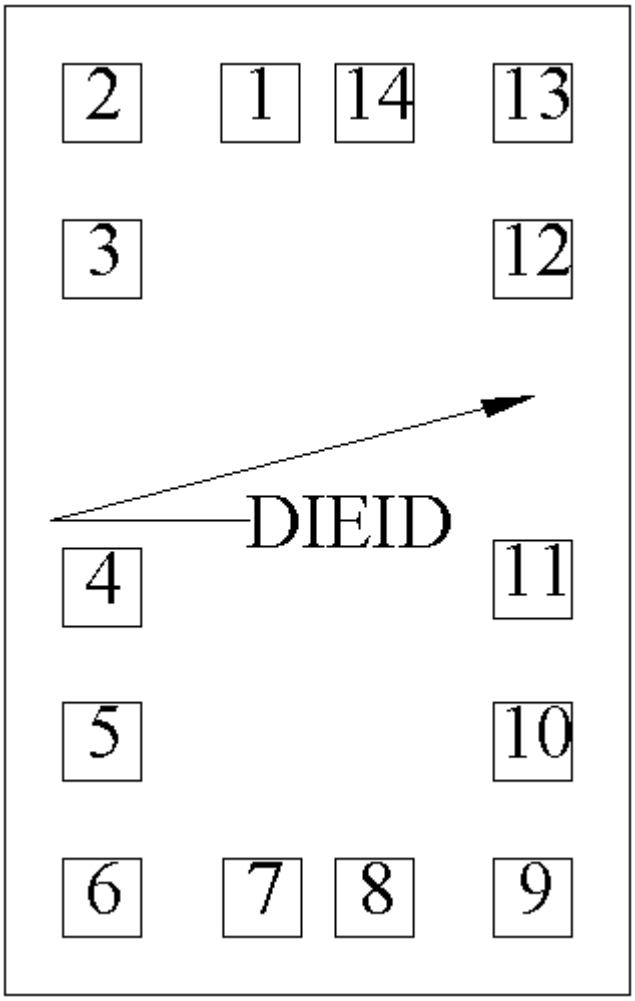
LPV324 MDC MWC
QUAD GENERAL PURPOSE, LOW VOLTAGE, LOW POWER, RAIL-TO-RAIL OUTPUT OPERATIONAL AMPLIFIERS

October 23,2002

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	LPV324	Bond Pad Opening Size (min)	76µm x 76µm
Die Step	A	Bond Pad Metalization	0.5%COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	610µm x 965µm 24mils x 38mils	Back Side Connection	Floating
Thickness	254µm Nominal		
Min Pitch	109µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
OUT A	1	-56	389	76	x	76
INPUT A-	2	-209	389	76	x	76
INPUT A+	3	-209	236	76	x	76
V+	4	-209	-84	76	x	76
INPUT B+	5	-209	-234	76	x	76
INPUT B-	6	-209	-387	76	x	76
OUTPUT B	7	-54	-387	76	x	76
OUTPUT C	8	56	-387	76	x	76
INPUT C-	9	211	-387	76	x	76
INPUT C+	10	211	-234	76	x	76
V-	11	211	-77	76	x	76
INPUT D+	12	211	236	76	x	76
INPUT D-	13	211	389	76	x	76
OUTPUT D	14	56	389	76	x	76

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